

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Hak Seong Kim	04/21/2008
Bong Hoe Kim	04/21/2008
Dong Wook Roh	04/21/2008
Joon Kui Ahn	04/21/2008
Dong Youn Seo	04/21/2008
RECEIVING PARTY DATA	
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Street Address:	20, Yoido-dong, Youngdungpo-gu
City:	Seoul
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Postal Code:	150-010
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13038214
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Total Attachments: 2

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ASSIGNMENT

(1-8) *Insert Name(s) of Inventor(s)*

- (1) HAK SEONG KIM
- (2) BONG HOE KIM
- (3) DONG WOOK ROH
- (4) JOON KUI AHN
- (5) DONG YOUN SEO
- (6)
- (7)
- (8)

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(9) *Insert name of Assignee*

(9) **LG ELECTRONICS INC.**

(10) *Insert state of Incorporation of Assignee*

(10) **Korea**

(11) *Insert address of Assignee*

(11) 20 Yoido-dong, Youngdungpo-gu, Seoul, 150-010, Korea

(hereinafter designated as the Assignee) the entire worldwide right, title and interest in the invention known as

(12) *Insert identification of Invention, such as Title, Case Number or Foreign Application Number*

(12) **AN APPARATUS AND METHOD FOR RECEIVING SIGNALS IN MULTI-CARRIER MULTIPLE ACCESS SYSTEMS (Application no. 11/913,539)**

for which the undersigned has (have) executed an application for patent in the United States of America and all patent applications in foreign countries corresponding thereto or based thereon.

(13) *Insert Date of Signing of Application*

(13) April 21, 2008

1) The undersigned agree(s) to execute all papers necessary in connection with any original, reissue, divisional and continuing United States and foreign applications for the above-identified invention and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to execute all papers and documents and perform any act which may be necessary in connection with claims or provisions of the International Convention for Protection of Industrial Property or similar agreements.

4) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed any agreement in conflict herewith.

The undersigned hereby appoints **the Attorneys associated with Customer No. 035884** the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: 21 April 2008 Signature of Inventor: [Signature]
Date: 21. Apr. 2008 Signature of Inventor: [Signature]
Date: 21 Apr 2008 Signature of Inventor: [Signature]
Date: 21 Apr 2008 Signature of Inventor: [Signature]
Date: 21 Apr. 2008 Signature of Inventor: [Signature]
Date: _____ Signature of Inventor: _____